

MBR30U60FCT

Low Vf Schottky Barrier Rectifiers



Voltage: 60 Volts

Current: 30 Amperes

Package: ITO-220AB

Features

- NH'S Low Vf Schottky Barrier Chip Technology
- Super Low Forward Voltage Drop For High Efficiency
- Low Power Loss For High Reliability
- High Frequency Switching Speed

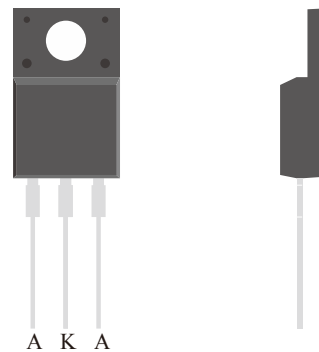
Mechanical Data

- **Case:** Molded With UL-94 ClassV-0 Recognized, RoHS-Compliant
- **Polarity:** Look At The Diagram And Polarity On The Right
- **Terminals:** Tin Plated Leads,Solderable Per J-STD-002 And JESD22-B102

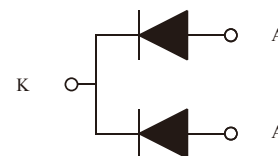
Typical Applications

- Switch Mode Power Supplies (SMPS)
- Fast Chargers
- LED Driver And Monitor Lighting
- Automotive Electronics And Charging Posts

Diagram:



Polarity:



Single Phase,Half Wave,60Hz,Resistive Or Inductive Load.For Capacitive Load,Derate Current By 20%

Maximum Ratings (Ta=25°C Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Ratings	Unit
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	60	V
Maximum RMS Voltag		V_{RMS}	42	V
Maximum DC Blocking Voltage		V_{DC}	60	V
Maximum Average Forward Rectified Current	Per Diode Total device	$I_{F(AV)}$	15 30	A
Peak Forward Surge Current Per Diode	8.3ms Single Half Sine-wave Superimposed On Rate Load	I_{FSM}	280	A
Current Squared Time Per Diode	$t < 8.3ms$	I^2t	325.4	A ² sec
Maximum Mounting Torque	M3 screw	T_{MM}	1.1	N.m

Electrical Characteristics (Ta=25°C Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Ratings			Unit
			Min.	Typ.	Max.	
Instaneous Forward Voltage Per Diode	Ta=25°C	$I_F = 15.0 A$	--	0.55	0.6	V
	Ta=100°C		--	0.51	0.56	
Maximum DC Reverse Current at Rated DC Blocking Voltage	Ta=25°C , $V_R = V_{RRM}$	I_{RRM}	--	10	100	uA mA
	Ta=100°C , $V_R = V_{RRM} * 80\%$		--	1	13	
Typical Junction Capacitance Per Diode	4 V,1MHz	C_J	--	1800	--	pF

Thermal Characteristics (Ta=25°C Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Ratings	Unit
Operating Junction Temperature Range		T_J	-55 to 150	°C
Storage Temperature Range		T_{STD}	-55 to 150	
Thermal Resistance Junction To Ambient With Steady-State	Still Air Environment With Ta=25°C	$R_{\theta JA}$	62.5	°C/W
Thermal Resistance Junction-Case With Steady-State	Device Mounted On 75mm x 45mm x 2.5mm Alu. Heat.	$R_{\theta JC}$	3.0	

Notes: 1.Pulse Test: 300 Us Pulse Width,1% Duty Cycle

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Typical Characteristics Curves

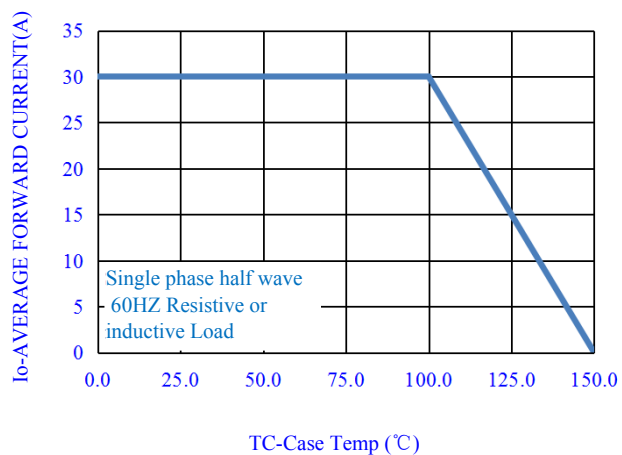


Fig.1-FORWARD CURRENT DERATING CURVE

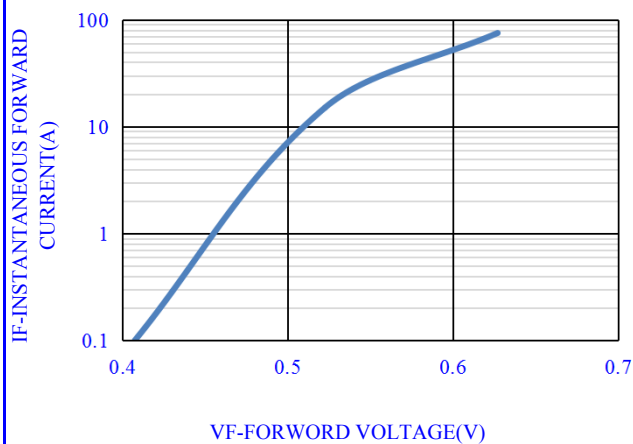


Fig.2- TYPICAL INSTANTANEOUS FORWARD

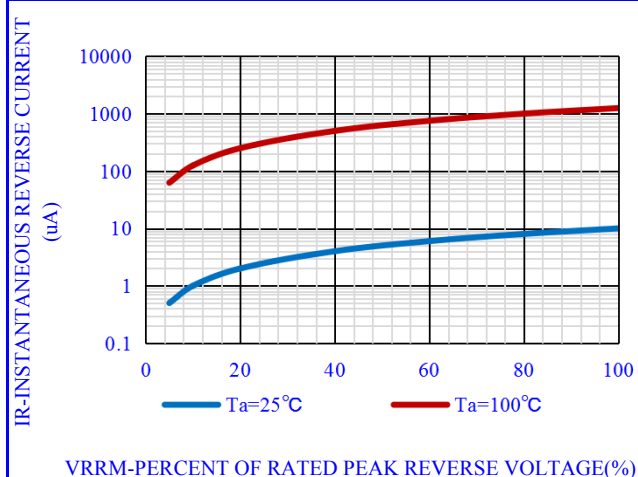


Fig.3- TYPICAL REVERSE CHARACTERISTICS

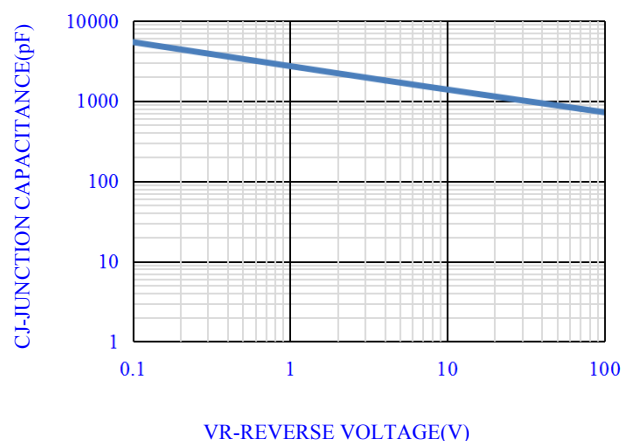


Fig.4- TYPICAL JUNCTION CAPACITANCE

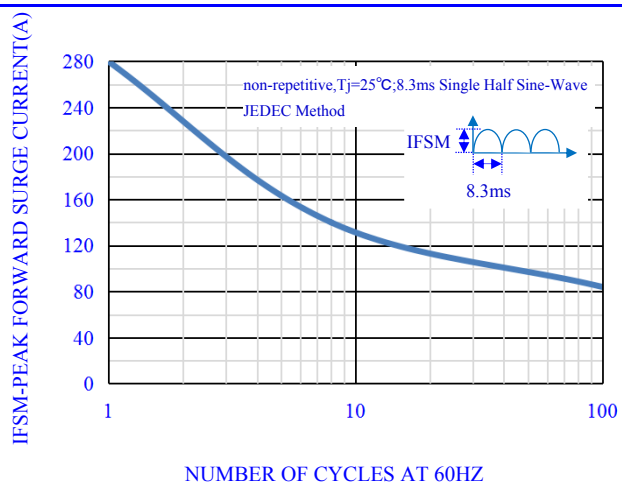


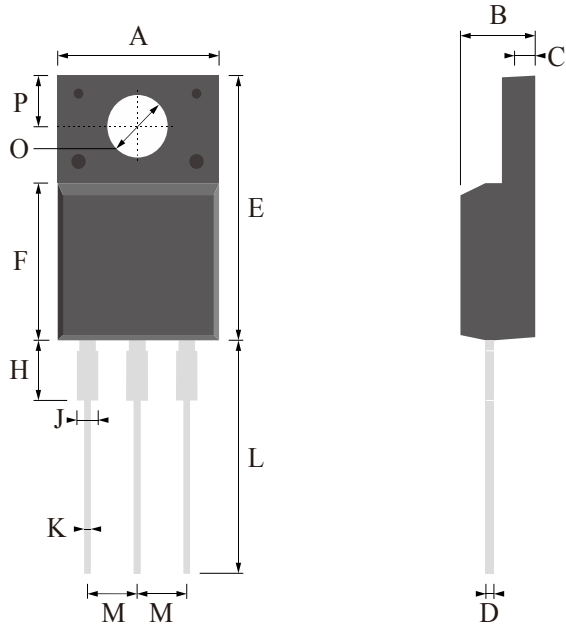
Fig.5-MAX. NON-REPETITIVE SURGE CURRENT

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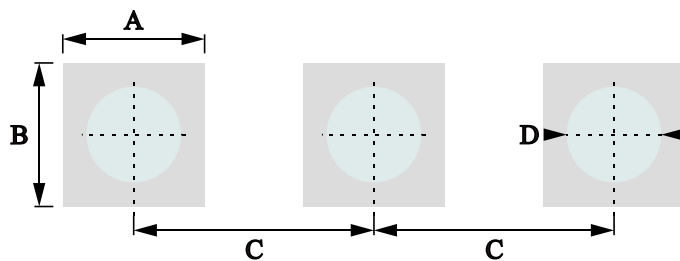
OUTLINE DRAWINGS



ITO-220AB

OUTLINE DIMENSIONS						
Dim.	Milimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	9.25	-	10.75	0.3642	-	0.4232
B	3.95	-	4.95	0.1555	-	0.1949
C	2.75	-	3.35	0.1083	-	0.1319
D	0.45	-	0.85	0.0177	-	0.0335
E	14.15	-	16.15	0.5571	-	0.6358
F	7.65	-	9.15	0.3012	-	0.3602
L	12.55	-	14.55	0.4941	-	0.5728
H	3.40	-	4.00	0.1339	-	0.1575
J	1.05	-	1.45	0.0413	-	0.0571
K	0.40	-	0.70	0.0157	-	0.0276
M	2.20	-	3.00	0.0866	-	0.1181
O	2.85	-	3.65	0.1122	-	0.1437
P	2.50	-	3.10	0.0984	-	0.1220

RECOMMEDND LAYOUT DRAWINGS



ITO-220AB

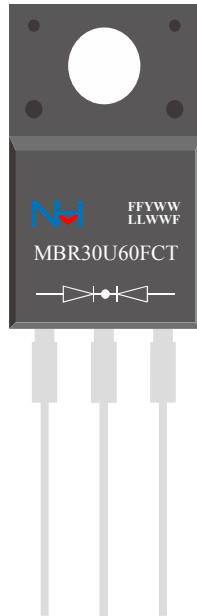
OUTLINE DIMENSIONS						
Dim.	Milimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	1.60	-	-	0.0630	-
B	-	1.60	-	-	0.0630	-
C	-	2.54	-	-	0.1000	-
D	-	1.00	-	-	0.0394	-

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MARKING



MARKING INSTRUCTION

NH=Niuhan Trademark
FF=Product Line Code,According To Actual Changes
YWW=Date Code,According To Actual Changes
LLWWF=Inernal Code,According To Actual Changes
MBR30U60FCT=Model

PACKING INFORMATION

Package Type	Package Code	Product Weight Approx(g/Pcs)	Package Method	Quantity (Pcs/Min. Pack.)	Quantity (Pcs/Inner Box)	Quantity (Pcs/Carton)
ITO-220AB	P1	1.715	Tube	50	1000	5000

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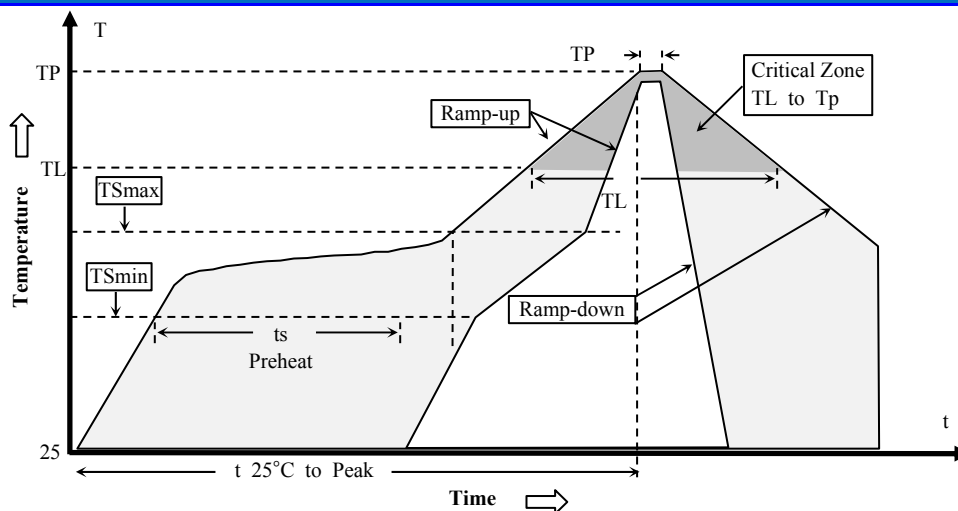
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Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat -Temperature Min(TS min) -Temperature Max(TS max) -Time(ts min to ts max)	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: -Temperature (TL) - Time (tL)	183°C 60-150 seconds	217°C 60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

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